

Average Weight : 1.2750 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silver Epoxy					0.003012	0.23624%
	Silver	7440-22-4	85.3		0.002569	
	Epoxy resin	Trade Secret	5.4		0.000163	
	Organic anhydride	Trade Secret	3.1		0.000093	
	A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxyp	-	3.1		0.000093	
	Anhydride	Trade Secret	3.1		0.000093	
Die					0.018207	1.42800%
	Silicon	7440-21-3	100.00		0.018207	
Gold Wire					0.004401	0.34518%
	Gold	7440-57-5	99.0475		0.004359	
	Palladium	7440-05-3	0.95		0.000042	
	Calcium	7440-70-2	0.002		0.000000	
	Beryllium	7440-41-7	0.0005		0.000000	
					1.099050	86.20000%
Mold Compound	Epoxy Resin	Trade Secret	7		0.076934	
	Phenol Resin	Trade Secret	7		0.076934	
	Silica(Amorphous) A	60676-86-0	80		0.879240	
	Silica(Amorphous) B	7631-86-9	5.45		0.059898	
	Carbon Black	1333-86-4	0.55		0.006045	
					0.006000	0.47059%
Leadframe Tape	NBR	9003-18-3	14		0.000840	
	Phenol resin	28453-20-5	14		0.000840	
	Bismaleimide	79922-55-7	14		0.000840	
	Polyimide film	Trade Secret	58		0.003480	
					0.144330	11.32000%
Leadframe	Nickel Plating	7440-02-0	0.325		0.000469	
	Palladium Plating	7440-05-3	0.0175		0.000025	
	Gold Plating	7440-57-5	0.004		0.000006	
	Copper	7440-50-8	95.5535		0.137912	
	Magnesium	7439-95-4	0.175		0.000253	
	Silicon	7440-21-3	0.725		0.001046	
	Nickel	7440-02-0	3.2		0.004619	

Revision History

Date	Version	Description of Revisions
3/9/2020	1.0	Initial Xilinx release (XCN18024)

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